Product Category: Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]
HP 2311gt 3D LCD Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0 (LED Backlight)</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1: Crossing Screwdriver</td>
<td>#1 &amp; #2</td>
</tr>
<tr>
<td>Description #2: Bushing Screwdriver</td>
<td>(HEX 5.5MM)</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Lay the Monitor on the desk. Unlock the 2 screws which used to fix the stand with backcover
2. Take out the bezel with hand.
3. Take out the keypad PCBA with Screw Driver
4. Take out the backcover with hand. Then take out the Tape and Foil with hand.
5. Unlock the 4 screws which used to fix the panel with Chassis
6. Take out the LED light connector, then remove the FFC connector from Panel.
7. Separate chassis assembly and panel, remove the FFC wire from PCBA
8. Unlock the 4 screws which fix the IF board to the chassis, unlock the 2 screws which fix power socket to the chassis
9. Remove the USB bracket, Unlock the 3 screws, Unlock the 7 screws which fix the IF & Power PCBA

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. 2311gt monitors System disassembly methods:

2. 2311gt LGD Panel (LM230WF8-TLA3) disassembly methods:
<table>
<thead>
<tr>
<th>Action</th>
<th>Tool</th>
<th>Photo</th>
</tr>
</thead>
<tbody>
<tr>
<td>Remove the stand</td>
<td>#2 Crossing Screw Driver</td>
<td>![Image]</td>
</tr>
<tr>
<td>Remove the base</td>
<td>N/A</td>
<td>![Image]</td>
</tr>
<tr>
<td>Remove the hinge cover</td>
<td>N/A</td>
<td>![Image]</td>
</tr>
<tr>
<td>Remove the hinge</td>
<td>#2 Crossing Screw Driver</td>
<td>![Image]</td>
</tr>
<tr>
<td>Remove the front bezel with Hand</td>
<td>N/A</td>
<td>![Image]</td>
</tr>
<tr>
<td>Step</td>
<td>Notes</td>
<td></td>
</tr>
<tr>
<td>----------------------------------------------------</td>
<td>-------</td>
<td></td>
</tr>
<tr>
<td>Remove the LVDS with Hand.</td>
<td>N/A</td>
<td></td>
</tr>
<tr>
<td>Remove the FFC line</td>
<td>N/A</td>
<td></td>
</tr>
<tr>
<td>Remove the Panel</td>
<td>N/A</td>
<td></td>
</tr>
<tr>
<td>Take out the chassis mylar form chassis</td>
<td>N/A</td>
<td></td>
</tr>
<tr>
<td>Step</td>
<td>Instructions</td>
<td></td>
</tr>
<tr>
<td>----------------------------------------------------------------------</td>
<td>------------------------------------------------------------------------------</td>
<td></td>
</tr>
<tr>
<td>1. Unlock the 2 hooks which fix the chassis on the rear cover</td>
<td>Use a #2 Crossing Screw Driver.</td>
<td></td>
</tr>
<tr>
<td>2. Take out the keypad from rearcover</td>
<td>N/A</td>
<td></td>
</tr>
<tr>
<td>3. Unlock the 3 screws which fix the PCBA on the chassis</td>
<td>Use a #2 Crossing Screw Driver.</td>
<td></td>
</tr>
<tr>
<td>4. Unlock the 4 screws which fix the DVI and VGA on the chassis</td>
<td>Use a #2 Crossing Screw Driver.</td>
<td></td>
</tr>
<tr>
<td>Action</td>
<td>Result</td>
<td></td>
</tr>
<tr>
<td>--------------------------------------------</td>
<td>--------</td>
<td></td>
</tr>
<tr>
<td>Take the PCBA from the chassis</td>
<td>N/A</td>
<td></td>
</tr>
<tr>
<td>Remove the LVDS, keypad and FFC line from PCBA</td>
<td>N/A</td>
<td></td>
</tr>
</tbody>
</table>
Method of LCM disassembly on LM230WF8-TLA3

Step 1 : Remove the Al coating Cover shield
Step 2 : Dismantle the Case top
Step 3 : Separate Case top (push the case top because of damages on COF)
Step 4 : Separate Board Ass'y
Step 5 : Loosen the screw (6Point)
Step 6 : Remove G/Panel
Step 7 : Remove Optical Sheet
Step 8 : Remove LGP Ass'y
Method of LCM disassembly on LM230WF8-TLA3

Step 9: Separate LED Array from C/Bottom Ass'y

Final: LED Array